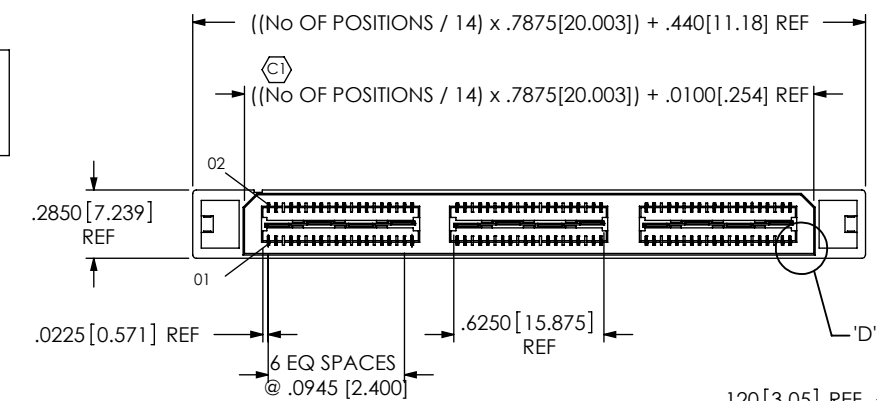


FIG. 1  
 QSE-042-01-X-D-DP-EMX SHOWN  
**ASO ONLY (APPLICATION SPECIFIC ORDER)**

DO NOT  
 SCALE FROM  
 THIS PRINT



**QSE-XXX-01-X-D-DP-EMX-XX**

**No OF PAIRS**  
 -014, -028, -042  
 \*\* -056, \*\* -070  
 (PER ROW)  
 \*\* SEE NOTE 11

**LEAD STYLE**  
 -01: .1380[3.505]

**PLATING SPECIFICATION**  
 -F: FLASH SELECTIVE GOLD WITH MATTE TIN TAILS (SEE NOTE 6) (USE C-162-XX-F & T-1G13-01-F)  
 -L: LIGHT SELECTIVE GOLD WITH MATTE TIN TAILS (USE C-162-XX-L & T-1G13-01-L)  
 -H: HEAVY GOLD WITH GOLD LEADS (USE C-162-XX-H & T-1G13-01-G)

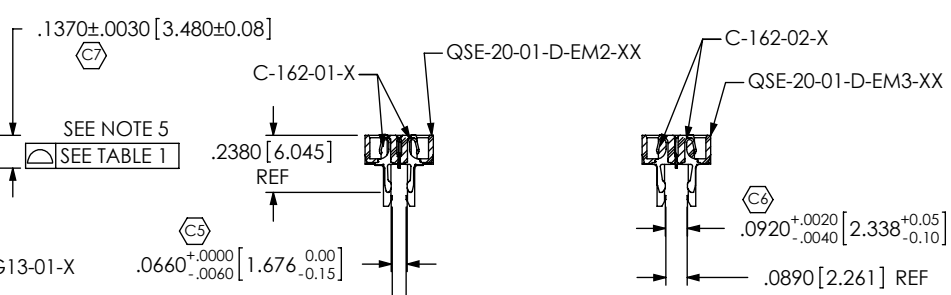
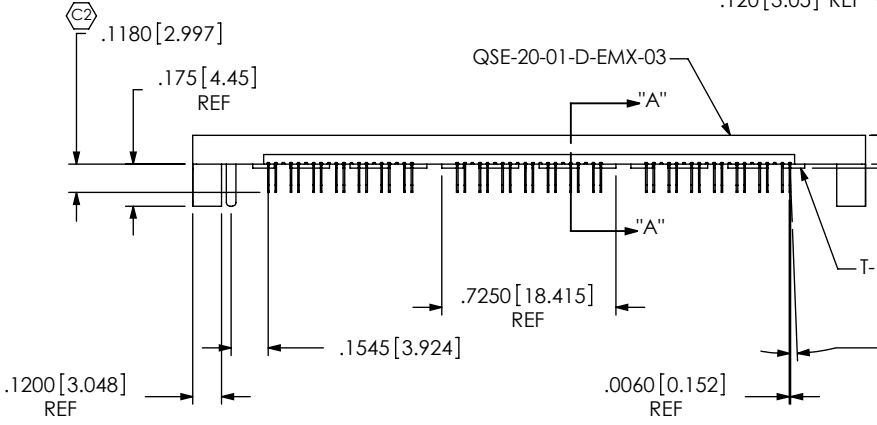
**OPTION**  
 \* -GP: GUIDE POST (SEE FIG.3, SHEET 2)  
 \* EM3-GP=NOT TOOLED

**EDGE MOUNT THICKNESS**  
 -EM2: .064[1.63] +/- .004 PCB (USE QSE-20-01-D-EM2-XX & C-162-01-X)  
 -EM3: (USE QSE-20-01-D-EM3-XX & C-162-02-X) **SEE NOTE 10**

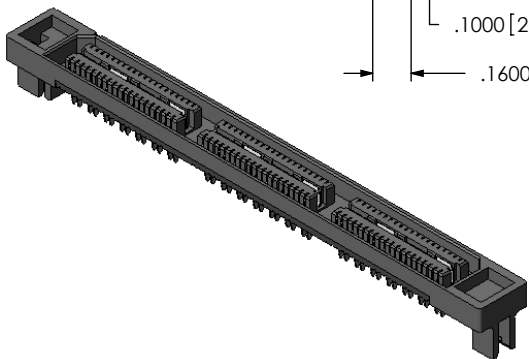
**DIFFERENTIAL PAIR**

**ROW SPECIFICATION**  
 -D: DOUBLE (USE QSE-20-01-D-EMX-XX)

**No OF BANKS**



- NOTES:
1. (C) REPRESENTS A CRITICAL DIMENSION.
  2. CONTACT RETENTION: 6 OZ MIN.
  3. GROUND PLANE RETENTION: 8 OZ MIN.
  4. PARTS ARE MOLD TO POSITION.
  5. MAX VARIANCE OF .002[.05].
  6. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING; -G GROUND PLANE PLATING CAN BE SUBSTITUTED FOR -F GROUND PLANE PLATING.
  7. NOTE DELETED.
  8. BOARD THICKNESS TO BE MEASURED FROM SOLDER PAD TO SOLDER PAD.
  9. SEE [http://www.samtec.com/processing/edgemt\\_tectalk/index.htm](http://www.samtec.com/processing/edgemt_tectalk/index.htm) FOR INFORMATION ON PROCESSING EDGE MOUNT PARTS.
  10. -EM3 IS NOT A STANDARD OFFERING; AVAILABLE AS AN ASP ONLY. PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP WITH ORDER INQUIRIES
  11. FOR NEW APPLICATIONS REQUIRING THESE POSITIONS, PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP.



**TABLE 1**

No OF PAIRS	GND PLANE COPLANARITY	ASSEMBLY BOW
-014 THRU -042	.004 [.10]	.004 [.10]
-056 THRU -070	.005[1.27]	.005[1.27]

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES. TOLERANCES ARE:  
 DECIMALS ANGLES  
 .XX: ±.01[.3]  
 .XXX: ±.005[.13]  
 .XXXX: ±.0020[.051]

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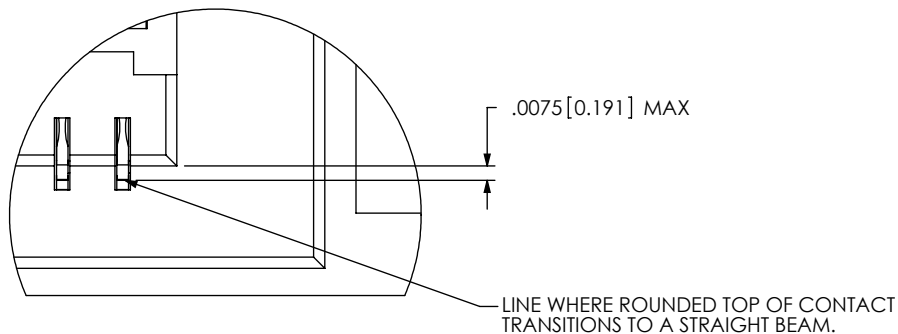
**samtec**

520 PARK EAST BLVD, NEW ALBANY, IN 47150  
 PHONE: 812-944-6733 FAX: 812-948-5047  
 e-Mail: info@SAMTEC.com code: 55322

**MATERIAL:** DO NOT SCALE DRAWING SHEET SCALE: 1:25:1  
 INSULATOR: LCP, COLOR: BLACK  
 CONTACT: PHOS BRONZE  
 GROUND PLANE: PHOS BRONZE

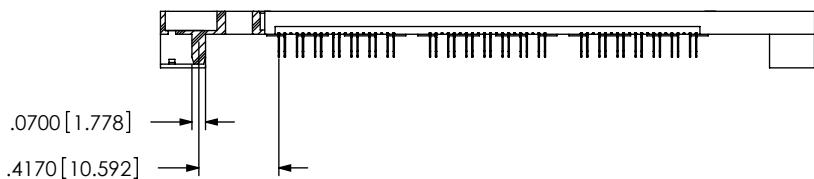
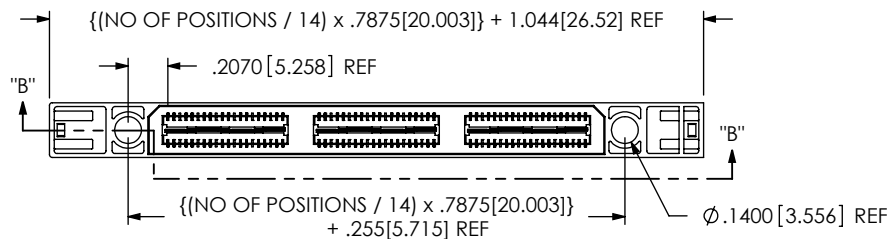
DESCRIPTION:  
 .8mm EDGEMOUNT DIFF PAIR HS SOCKET ASSEMBLY  
 DWG. NO.  
**QSE-XXX-01-X-D-DP-EMX-XX**

BY: DEAN P 4/10/2001 SHEET 1 OF 2



DETAIL 'D'  
SCALE TO : 1

FIG. 3  
-GP OPTION  
(SAME AS FIG. 1, UNLESS OTHERWISE STATED)  
(42 POSITION MAX)  
(ONLY AVAILABLE WITH -EM2 OPTION)



SECTION "B"-"B"  
SCALE 1 : 1

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DO NOT SCALE DRAWING

SHEET SCALE: 2:1



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PHONE: 812-944-6733 FAX: 812-948-5047  
e-Mail: info@SAMTEC.com code: 55322

DESCRIPTION:  
.8mm EDGEMOUNT DIFF PAIR HS SOCKET ASSEMBLY

DWG. NO.  
QSE-XXX-01-X-D-DP-EMX-XX

BY: DEAN P 4/10/2001 SHEET 2 OF 2